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Integration of bright color centers into arrays of silicon carbide nanopillars

E. Vuillermet,¹ N. Bercu,² S. Kochtcheev,¹ and M. Lazar¹

¹⁾Light nanomaterials, nanotechnologies laboratory, CNRS UMR 7076, University of Technology of Troyes, Troyes, France

²⁾Light nanomaterials, nanotechnologies laboratory, CNRS UMR 7076, University Reims Champagne-Ardenne, Reims, France

(*Electronic mail: enora.vuillermet@utt.fr)

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Silicon carbide (SiC) is a wide-bandgap semiconductor combining mature fabrication processes with the ability to host optically active point defects, called color centers, making it ideal for quantum technologies. This study focuses on silicon vacancy defects in 4H-SiC, integrated into nanopillar arrays fabricated via ion implantation, e-beam lithography, and reactive ion etching. SiC nanopillars with a height of $1.4\mu m$ are formed and arrays with varying pillar diameters and spacings are obtained. Cathodoluminescence measurements at 80 K reveal a 2–4 times improvement in light collection efficiency from the defects compared to unstructured SiC. The cathodoluminescence intensity increases with a smaller pillar spacing and a larger diameter. These findings demonstrate the potential of SiC nanopillar arrays as scalable platforms for enhancing quantum photonic device performance.

Silicon carbide (SiC) is a wide-bandgap semiconductor that has been used for decades in power device applications¹. The maturity of its fabrication processes has resulted in the commercialization of high-quality wafers with minimal defects², enabling the controlled integration of point defects within the material. This has recently driven the development of SiC as a host for bright color centers with long spin coherence times for quantum applications^{3,4}.

Compared to other materials, such as diamond and rare-earth-doped semiconductors, SiC offers significant advantages for quantum device fabrication due to its wellestablished processes, including epitaxial growth⁵, doping (n and p-type)⁶, and etching⁷. These make SiC an ideal candidate for developing quantum platforms and devices^{8,9}, such as magnetic field sensors¹⁰, quantum computing systems¹¹, and single-photon sources (SPSs) integrated into electronic or CMOS devices¹². However, due to the high refractive index of SiC compared to air (around 2.65)¹³, light emitted from the color centers is predominantly reflected at the SiC/air interface, leading to the need for devices that isolate single-photon sources while increasing the intensity of light collected. Previous studies have demonstrated that integrating color centers into photonic structures, such as microdisks¹⁴, optical cavities¹⁵, or nanopillars¹⁶, can achieve these objectives.

In this work, we focus on the single silicon vacancy defect (V_{Si}) in 4H-SiC, a promising quantum defect with electronic spin states that can be manipulated at room temperature (RT), exhibiting spin coherence times of approximately 100 μ s at RT¹⁷ and up to 20ms at cryogenic temperatures¹⁸. To enhance the light collection efficiency of these color centers, we incorporate them using ion implantation into nanopillar arrays fabricated on 4H-SiC substrates. This study completes the work of S. Castelletto et al.¹⁹ and M. Radulaski et al.¹⁶ and ensures that the silicon vacancies are generated exclusively within the nanopillars, avoiding defect formation in the substrate between the photonic structures. Additionally, we investigate the effects of varying pillar spacings on light collection efficiency, which has not been done experimentally until now to the best of our knowledge. Using cathodoluminescence (CL) at 80 K, we demonstrate a 2-4 times improvement in the light collection from the silicon vacancies compared to an unstructured SiC substrate. These results highlight the potential of SiC nanopillar arrays as a scalable platform for quantum photonic applications.

Fabrication. The nanopillars are fabricated on 4H-SiC ndoped substrates, first implanted with helium ions at an energy of 120 keV and a dose of $4 \times 10^{17} cm^{-2}$. SRIM-TRIM simulations^{20,21} indicate that the silicon vacancies are primarily generated at a depth of 480nm (FIG.1).



FIG. 1. SRIM-TRIM simulations depth profiles of the helium ions introduced and silicon vacancies generated during ion implantation.

One sample is kept as a reference while the other one is processed to form the nanopillar arrays. For the latter, electron beam (e-beam) lithography is performed using a Raith eline scanning electron microscope (SEM) operating at 20keV with an aperture of 30 μ m and an exposure dose of 200 μ C/cm². For this step, a 450 nm-thick PMMA resist is used to pattern the samples and is developed, after e-beam exposure, into a solution of MIBK:IPA for 1min20s. Following this, a 150nm-thick chromium hard mask is deposited via electron beam evaporation at a deposition rate of 0.1nm/s using the



FIG. 2. Fabrication steps of the 4H-SiC nanopillars.

MEB400 system from Plassys. Lift off of the mask occurs in a solution of acetone under agitation. Reactive ion etching with inductively coupled plasma (RIE/ICP) is then carried out in a MU400 system of Plassys to form the SiC pillars. The plasma is generated at low pressure (1.067Pa) using a gas mixture of 10sccm SF₆ and 2sccm O₂, with 100W of RIE power and 1000W of ICP power. The unit "sccm" stands for Standard Cubic Centimeters per Minute. An etching speed of 4.7nm/s is achieved under a bias of -156V. To avoid micromasking, a phenomenon where small particles or residues act as unintended masks, leading to non-uniform etching and the formation of rough uneven surfaces^{22,23}, a 100nm-thick silicon layer is deposited on the samples before SiC etching. After etching, the remaining chromium mask is removed using a chromium etchant solution. The plasma etching parameters were optimized through multiple experiments designed to etch SiC power devices²⁴. Fabrication steps of the 4H-SiC nanopillar arrays are summarized in FIG.2. Further details are provided in the Supplementary Materials of this paper.

The resulting SiC nanopillars (FIG.3) have a height of 1.4µm, with diameters ranging from 350 to 700nm. The arrays have an area of $100 \times 100 \mu m^2$, with pillar spacings of 336nm, 538nm, 946nm, or 5µm, as determined by the simulations presented in the paper of M.A. Ahamad *et al.*²⁵. The conical shape of the chromium masks (FIG.3), combined with lateral etching during the fabrication process, contribute to a reduction in the pillar diameter (Supplementary Materials). This effect is more pronounced for arrays with larger pillar spacings (945nm and 5µm). This lateral etching, negligible during SiC power device processing, is significant in nanostructure fabrication and leads to the so-called bowing phenomenon^{15,26}. Bowing refers to lateral etching or undercutting of the pillars' sidewalls, resulting

in a curved or bowed profile rather than straight vertical sidewalls. Despite the pillar distortion, there is no evidence of micro-masking or trenching, thanks to the addition of the Si layer, which enhances the volatility of reaction by-products during plasma etching²³. Trenching can be caused by ion scattering, over-etching, or charge buildup and manifests as deep, narrow grooves ("trenches") at the base or sidewalls of etched features during anisotropic plasma etching^{7,27}.

Cathodoluminescence measurements. Cathodoluminescence offers an alternative to photoluminescence by generating electron-hole recombination through electron beam excitation rather than laser excitation^{28,29}. CL measurements are performed using a SPARC system (Delmic) integrated with a JEOL JSM-7900F SEM to identify the color centers created by ion implantation. The samples are characterized at 80K, the low temperature being maintained by a liquid nitrogen circulation system (80K Cryo-module, Kammrath and Weiss GmbH, Schwerte, Germany). Α diffraction grating of 302 lines/mm with a central wavelength of 500nm is used for spectral analysis. The SEM is operated at an acceleration voltage of 15kV with a beam current of 1nA. The CL system's spectral detection range extends up to 1100nm, allowing detailed analysis of the emitted light from the silicon vacancies.

Silicon vacancies identification. Since the electron beam is focused on a precise point on the sample surface (around 1.5nm of diameter), the intensity of collected light from the V_{Si} defects varies depending on the area analyzed. FIG.4 illustrates various measurement points and their corresponding CL spectra for an array of nanopillars with a theoretical diameter of 500nm and a pillar spacing of 336nm. The typical CL

signal of the silicon vacancies appears around $900nm^{30}$, confirming the presence of the defects within the SiC nanopillars. Because the silicon vacancy can occupy a cubic (k) or hexagonal (h) site of 4H-SiC³¹, two zero-phonon lines (ZPLs), called V1 (h) and V2 (k), are observed, at 850 and 908nm respectively. The wavelengths of the ZPLs are slightly blue-shifted compared to the expected values (862nm for V1 and 917nm for V2)³², probably due to the local strains within the 4H-SiC crystal after ion implantation. At the end, we observe that the intensity of the CL spectra is highest at the center of the pillar structures (FIG.4). Less expected, a CL signal is detected between the pillars, even with the lack of defects in this area, likely due to a resonance effect induced by the periodic array. Further measurements are thus realized with the electron beam focused at the center of the pillars.



FIG. 3. Scheme of the nanopillar arrays (a) and SEM images with no tilt (b) and a 30° tilt (c) of the Cr-masks for a pillar diameter of 450nm and a spacing of 5 μ m. SEM images of the nanopillar arrays are also shown for a pillar diameter of 700nm and a spacing of 336nm (d), 538nm (e), 946nm (f) and 5 μ m (g). Images (h) and (i) are the respective zoom of images (d) and (g).



FIG. 4. SEM images under electron scanning of an array with a pillar diameter of 450nm and a spacing of 336nm (a-c). The normalized CL spectra (d) are measured at the positions 1 to 3.

Effect of arrays dimensions. As shown in FIG.5, the normalized CL spectra intensity from the V_{Si} defects increases with the pillar diameter for a given spacing between the pillars. This behavior can be attributed to a higher number of defects in larger-diameter pillars, resulting in enhanced excitation of the color centers. Unlike previous simulations and studies reported in the literature^{16,19}, no specific pillar diameter exhibits maximum luminescence for these defects. Additionally, the CL signal intensity increases as the pillar spacing decreases. Compared to the unprocessed reference sample, the signal is weaker in arrays with large spacings of 946nm and 5µm. This reduction is likely due to excessive lateral etching of the pillars, which distorts their vertical geometry and reduces their resonance with the silicon vacancies. In contrast, for smaller pillar spacings, particularly at 336nm, the CL intensity can double to quadruple depending on the pillar diameter compared to the reference sample without pillars. These findings confirm that the periodicity of the arrays significantly influences the intensity of light collected from the silicon vacancies. When the pillars are sufficiently close, a resonance effect occurs between the color centers and the array, enhancing the signal compared to the reference sample. Moreover, compared to previous experimental studies where the array periodicity was around $5\mu m^{16,19}$, we observed a lower photon collection efficiency than the unprocessed reference sample for larger pillar spacing. This discrepancy may stem from the fact that, unlike other studies, our fabrication process included etching the SiC sample after the ion implantation step. As a result, the silicon vacancies were generated exclusively within the pillars, without any of them present in the etched surface, apart from the intrinsic defects of the 4H-SiC substrate.



FIG. 5. CL normalized spectra of silicon vacancies for varying diameter (a) and spacings (b). The diameter is fixed at 500nm for the graphic (a) and the spacing is fixed at 336nm for the graphic (b).

This study highlights the potential of silicon carbide (SiC) nanopillar arrays as scalable and efficient platforms for enhancing light collection from color centers such as silicon vacancies in 4H-SiC. By combining color centers' generation and nanopillar fabrication, we demonstrate the compatibility of SiC with photonic structures designed for quantum applications. Due to the high applicability of ion implantation and plasma etching, this technological platform could also be adapted to integrate different color centers in other polytypes of SiC such as 3C or 6H-SiC.

While the results confirm the influence of pillar geometry and array periodicity on light collection efficiency, further work is needed to fully understand the underlying mechanisms. Numerical simulations could provide valuable insights into the role of array resonance in enhancing the light collection of the color centers. Additionally, experiments with isolated single V_{Si} defects are essential to confirm single-photon emission properties and assess the platform's potential for quantum technologies. Exploring arrays with even smaller spacings near 336nm would also help elucidate how the CL signal evolves as the pillars approach each other, potentially unlocking new regimes of photonic interaction. Finally, improvements in fabrication processes to minimize SiC lateral etching and preserve pillar integrity could further enhance device performance.

In conclusion, this work establishes a foundation for integrating quantum defects in SiC with photonic structures, paving the way for applications in quantum sensing, singlephoton sources, and scalable quantum photonic devices. Future studies addressing the above challenges will bring us closer to realizing the full potential of SiC for quantum technologies.

SUPPLEMENTARY MATERIALS

This part details the fabrication steps of the 4H-SiC nanopillar arrays and the evolution of lateral etching with pillars diameters and spacings.

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AUTHOR DECLARATION

Conflict of interest

The authors have no conflicts to disclose.

Authors contributions

E. Vuillermet: Conceptualization; Formal analysis; Investigation; Methodology; Validation; Writing – original draft. **S. Kochtcheev**: Investigation; Methodology. **N. Bercu**: Investigation; Methodology. **M. Lazar**: Conceptualization; Funding acquisition; Supervision; Validation; Writing – review and editing.

DATA AVAILABILITY STATEMENT

The data that support the findings of this study are available from the corresponding author upon reasonable request.

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